502665666 02/04/2014

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT2712274

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HONGSIK KIM	01/22/2014
HYUNJIN YOON	01/22/2014

RECEIVING PARTY DATA

Name:	LG Electronics Inc.	
Street Address:	20 Yeouido-dong Yeongdeungpo-gu	
City:	Seoul	
State/Country:	REPUBLIC OF KOREA	
Postal Code:	150-721	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29481292

CORRESPONDENCE DATA

 Fax Number:
 (202)739-3001

 Phone:
 2027393000

Email: patents@morganlewis.com, kcasavecchia@morganlewis.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name: ROBERT J. GAYBRICK

Address Line 1: 1111 PENNSYLVANIA AVE, NW

Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20004

ATTORNEY DOCKET NUMBER:	001364-7275
NAME OF SUBMITTER:	ROBERT J. GOODELL
Signature:	/Robert J. Goodell/
Date:	02/04/2014

Total Attachments: 1

 $source = 001364-7275_Assignment_02042014\#page1.tif$

PATENT REEL: 032160 FRAME: 0157

ASSIGNMENT

WHEREAS WE, the below named inventors, (hereinafter referred to as "Assignors"), have made an invention entitled:

Case for Cellular Phone

for which WE filed an application of United States on

, (Application No

; and

WHEREAS, LG ELECTRONICS INC., whose post office address is 20 Yeouido-dong Yeongdeungpo-gu, Seoul, 150-721, Republic of Korea (hereinafter referred to as "Assignee"), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filled for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Director of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, WE have hereunto set my hands.

Full Name of first Assignor	Hongsik Kim
Address	116-1102, Sungwon Apt., Sanghyeon-dong , Suji-gu, Yongin-si, Gyeonggi-do, Korea
Signature Signature	3/3
Date	January 22, 2014
Full Name of second Assignor	Hyunjin Yoon
Address	103-901, Dongbaek Apt., 849(29/2), Ojeon-dong, Uiwang-si, Gyeonggi-do, Republic of Korea
Signature	MAN /
Date	Jan 6 ary 22, 2014

Morgan, Lewis & Bockius UP

DH1:71340338.1

RECORDED: 02/04/2014